

Gunter Semiconductor GmbH

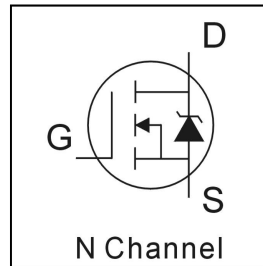
GFC048

N Channel Power MOSFET with extremely low RDS(on)

Chip Specification

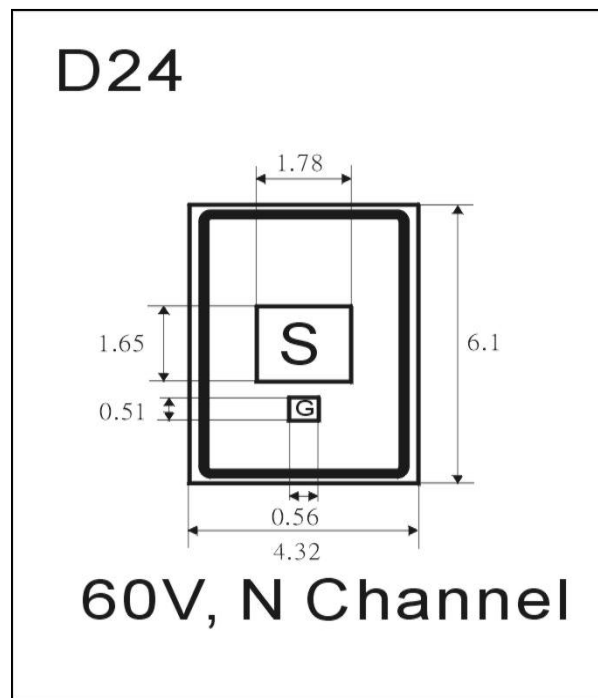
General Description:

- * Advanced Process Technology
- * Dynamic dV/dt Rating
- * **175°C Operating Temperature**
- * **Fast Switching**
- * **Fully Avalanche Rated**
- * **Extremely low Rds(on)**



Mechanical Data:

D24
Dimension 4.32mm x 6.10mm
Thickness: 400 μm
Metallization:
Top : : Al
Backside : CrNiAg / Au
Suggested Bonding Conditions:
Die Mounting: Solder Perform
95/5 PbSn or 92.5./2.5/5 PbAgIn
Source Bonding Wire: 20 mil Al



Absolute Maximum Rating

@Ta=25°C

Characteristics	Symbol	Limit	Unit	Test Conditions
Drain-to-Source Breakdown Voltage	V(BR)DSS	60	V	VGS=0V, ID=250μA
Static Drain-to - Source On-resistance	RDS(ON)	0.018	Ω	VGS=10V, ID=32A
Continuous Drain current (in target package)	ID@25°C	53	A	VGS=10V
Continuous Drain current (in target package)	ID@100°C	37	A	VGS=10V
Operation Junction	Tj	-55~175	°C	
Storage Temperature	TSTR	-55~175	°C	

Target Device: IRFZ48

TO-263AB

Pd 3.8 W @Ta=25°C
Pd 94 W @Tc=25°C